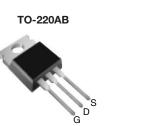
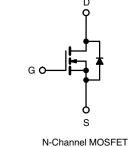


Vishay Siliconix

Power MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	400				
R _{DS(on)} (Ω)	V _{GS} = 10 V 1.0				
Q _g (Max.) (nC)	22				
Q _{gs} (nC)	5.8				
Q _{gd} (nC)	9.3				
Configuration	Single				





FEATURES

• Low Gate Charge Q_q results in Simple Drive Requirement



RoHS

COMPLIANT

- Improved Gate, Avalanche and Dynamic dV/dt Ruggedness
- Fully Characterized Capacitance and Avalanche Voltage and Current
- Effective Coss Specified
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply
- High Speed Power Switching

TYPICAL SMPS TOPOLOGIES

- Single Transistor Flyback Xfmr. Reset
- Single Transistor Forward Xfmr. Reset (Both US Line Input Only)

ORDERING INFORMATION			
Package	TO-220AB		
Lead (Pb)-free	IRF730APbF		
Leau (FD)-hee	SiHF730A-E3		
SnPb	IRF730A		
	SiHF730A		

PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V _{DS}	400	v	
Gate-Source Voltage			V _{GS}	± 30	v	
Continuous Drain Current	V _{GS} at 10 V	T _C = 25 °C	1-	5.5		
	V _{GS} at 10 V	T _C = 100 °C	ID	3.5	А	
Pulsed Drain Current ^a			I _{DM}	22		
Linear Derating Factor				0.6	W/°C	
Single Pulse Avalanche Energy ^b			E _{AS}	290	mJ	
Repetitive Avalanche Current ^a			I _{AR}	5.5	A	
Repetitive Avalanche Energy ^a			E _{AR}	7.4	mJ	
Maximum Power Dissipation	wer Dissipation $T_{\rm C} = 25 ^{\circ}{\rm C}$			74	W	
Peak Diode Recovery dV/dt ^c			dV/dt	4.6	V/ns	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	- 55 to + 150	°C	
Soldering Recommendations (Peak Temperature)	for ⁻	10 s	-	300 ^d	1	
Mounting Torque	6-32 or M3 screw			10	lbf ∙ in	
Mounting Torque				1.1	N · m	

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).

b. Starting $T_J = 25$ °C, L = 19 mH, $R_g = 25 \Omega$, $I_{AS} = 5.5 A$ (see fig. 12).

c. $I_{SD} \le 5.5$ Å, dl/dt ≤ 90 Å/µs, $V_{DD} \le V_{DS}$, $T_J \le 150$ °C.

d. 1.6 mm from case.

* Pb containing terminations are not RoHS compliant, exemptions may apply

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THERMAL RESISTANCE RAT	INGS							
PARAMETER	SYMBOL	TYP. MAX.		UNIT				
Maximum Junction-to-Case (Drain)	R _{thJC}	- 1.70 0.50 -			°C/W			
Case-to-Sink, Flat, Greased Surface	R _{thCS}							
Maximum Junction-to-Ambient	R _{thJA}	- 62				-		
SPECIFICATIONS (T _J = 25 $^{\circ}$ C, u	unless otherw	ise noted)						
PARAMETER	SYMBOL	TES	T CONDITI	ONS	MIN.	TYP.	MAX.	UNIT
Static		•						
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} :	= 0 V, I _D = 2	250 μA	400	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C,	I _D = 1 mA	-	0.5	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 2	250 μA	2.0	-	4.5	V
Gate-Source Leakage	I _{GSS}		$V_{GS} = \pm 30$	V	-	-	± 100	nA
Zero Gate Voltage Drain Current		$V_{DS} = 400 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$		₆ = 0 V	-	-	25	μA
Zero Gate Voltage Drain Gurrent	IDSS	V _{DS} = 320 \	V_{DS} = 320 V, V_{GS} = 0 V, T_{J} = 125 °C		-	-	250	
Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 10 \text{ V} \qquad \qquad I_D = 3.3 \text{ A}^b$		-	-	1.0	Ω	
Forward Transconductance	g fs	V _{DS}	= 50 V, I _D =	3.3 A	3.1	-	-	S
Dynamic								
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1.0 MHz, see fig. 5		-	600	-	pF	
Output Capacitance	C _{oss}			-	103	-		
Reverse Transfer Capacitance	C _{rss}			-	4.0	-		
Output Capacitance	6		$V_{DS} = 1.0$) V, f = 1.0 MHz	-	890 -		рг
Output Capacitance	C _{oss}	$V_{GS} = 0 V$ $V_{DS} = 3$		0 V, f = 1.0 MHz	-	30	-	
Effective Output Capacitance	C _{oss} eff.		$V_{DS} = 0$) V to 320 V ^c	-	45	-	
Total Gate Charge	Qg				-	-	22	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V		3.5 A, V _{DS} = 320 V	-	-	5.8	nC
Gate-Drain Charge	Q _{gd}		see fig	g. 6 and 13 ^b	-	-	9.3	
Turn-On Delay Time	t _{d(on)}				-	10	-	
Rise Time	t _r	$\begin{split} V_{DD} &= 200 \text{ V}, \text{ I}_{D} = 3.5 \text{ A} \\ \text{R}_{g} &= 12 \ \Omega, \text{ R}_{D} = 57 \ \Omega, \\ \text{see fig. } 10^{\text{b}} \end{split}$		_	22	-		
Turn-Off Delay Time	t _{d(off)}			-	20	-	ns	
Fall Time	t _f			-	16	-		
Drain-Source Body Diode Characteristi	cs	•				<u> </u>	I	
Continuous Source-Drain Diode Current	١ _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	5.5		
Pulsed Diode Forward Current ^a	I _{SM}			-	-	22	A	
Body Diode Voltage	V _{SD}	$T_J = 25 \ ^{\circ}C, \ I_S = 5.5 \ A, \ V_{GS} = 0 \ V^b$		-	-	1.6	V	
Body Diode Reverse Recovery Time	t _{rr}			-	370	550	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	- T _J = 25 °C, I _F = 3.5 A, dI/dt = 100 A/µs ^b			-	1.6	2.4	μC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-			-on is dor	ninated b	y L _S and	L _D)

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).

b. Pulse width \leq 300 µs; duty cycle \leq 2 %.

c. C_{oss} eff. is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}.

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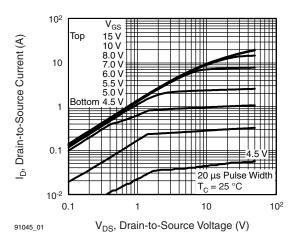


Fig. 1 - Typical Output Characteristics

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

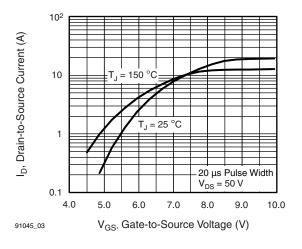


Fig. 3 - Typical Transfer Characteristics

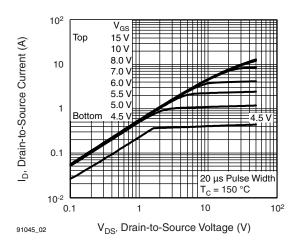


Fig. 2 - Typical Output Characteristics

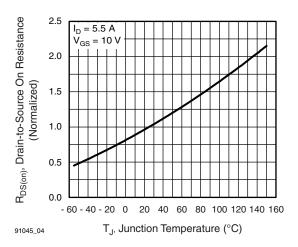


Fig. 4 - Normalized On-Resistance vs. Temperature

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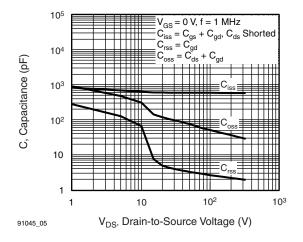


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

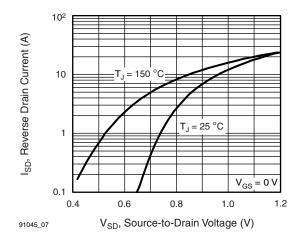


Fig. 7 - Typical Source-Drain Diode Forward Voltage

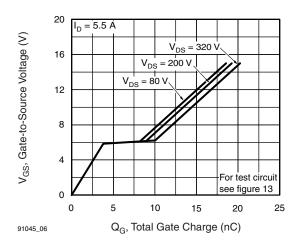


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

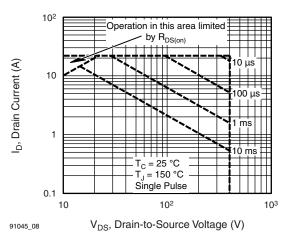


Fig. 8 - Maximum Safe Operating Area

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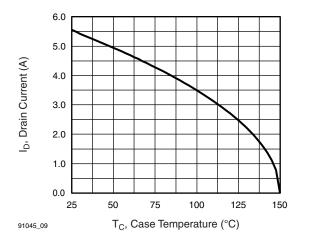


Fig. 9 - Maximum Drain Current vs. Case Temperature

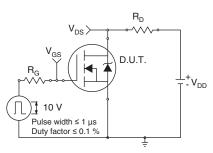


Fig. 10a - Switching Time Test Circuit

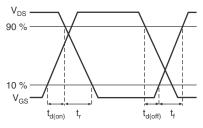


Fig. 10b - Switching Time Waveforms

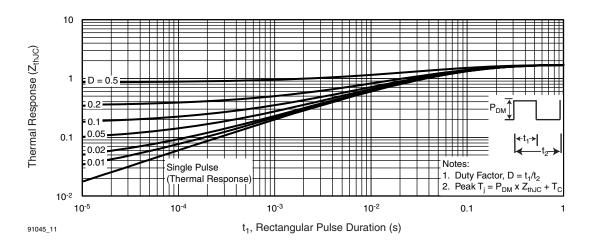


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

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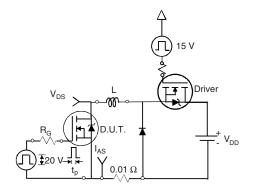


Fig. 12a - Unclamped Inductive Test Circuit

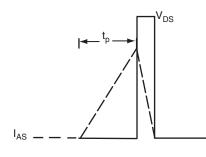


Fig. 12b - Unclamped Inductive Waveforms

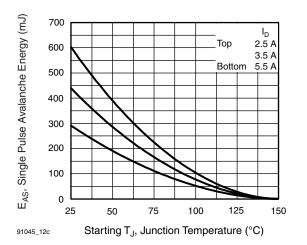


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

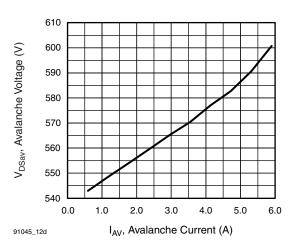


Fig. 12d - Typical Drain Source Voltage vs. Avalanche Current

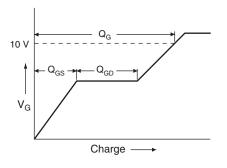


Fig. 13a - Basic Gate Charge Waveform

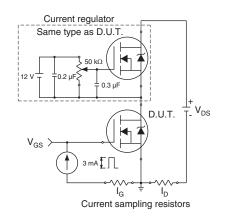


Fig. 13b - Gate Charge Test Circuit

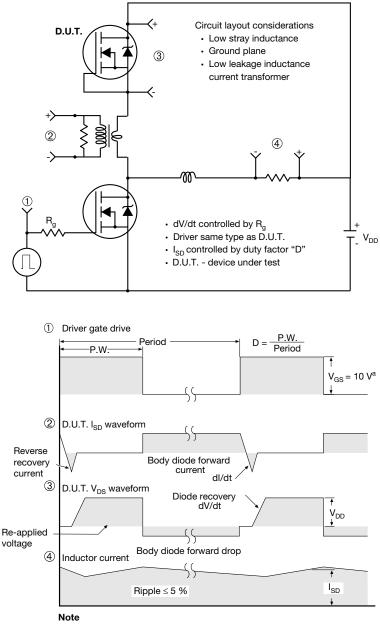
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a. $V_{GS} = 5$ V for logic level devices

Fig. 14 - For N-Channel

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TO-220-1



DIM.	MILLIN	IETERS	INCHES		
DIN.	MIN.	MAX.	MIN.	MAX.	
А	4.24	4.65	0.167	0.183	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
E	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.10	6.71	0.240	0.264	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØР	3.53	3.94	0.139	0.155	
Q	2.54	3.00	0.100	0.118	
ECN: X15-0364-Rev. C, 14-Dec-15 DWG: 6031					

Note

- M^{\star} = 0.052 inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM

Package Picture						
ASE		Xi'an				
		IRF 9510 744K AB				

Revison: 14-Dec-15

1 For technical questions, contact: <u>hvm@vishay.com</u> Document Number: 66542

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